

2021 CMPUG SPRING MEETING – AGENDA

Topic: Advances in CMP Consumables, Materials and Tools

Meeting Date: April 22, 2021

Time: 1:00 p.m. – 5:05 p.m. (Central Time)

Location: Virtual – Zoom Platform

Co-Chairs:

Michael Pevny, 3M, mpevny@mmm.com

Gene Davis, Texas Instruments, g-davis2@ti.com

The Chemical Mechanical Planarization Users Group (CMPUG) Symposium on Advances in CMP Consumables, Materials and Tools commences on **April 22, 2021**. The symposium will provide an international forum for academic researchers, industrial practitioners and engineers from around the world for the exchange of information on state-of-the-art research in CMP semiconductor technology. The CMPUG promotes the exchange of opportunities, ideas, friendly relationships and research collaboration. The areas of focus for this meeting will be the following:

- [CMP consumables and materials](#)
- [CMP Polishing and Metrology Tools](#)
- [CMP Process Integration](#)

SPEAKERS/AGENDA

1:00 p.m. Welcome and Acknowledgment of sponsors; by conf co-chairs Michael Pevny (3M) and Gene Davis (Texas Instruments)

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1:10 p.m. *Measuring Large Particle Contaminants in Cerium Oxide Chemical Mechanical Polishing, (CMP) Slurries with Total Holographic Characterization*, Laura A. Philips, **Spheryx, Inc**

1:35 p.m. *Slurry Injection System (SIS) Implementation in Dielectric and Metal CMP for III-V Semiconductors*, John Zabasajja, **HRL Laboratories**

2:00 p.m. *CMP Process Challenges for mmWave Si Technology*, Hong Jin Kim, **Global Foundries**

2:25 p.m. *Mixing and Handling Challenges with Next Generation Slurries*, Carlo Aparece, **Mega Fluid Systems** and Marc Maxim, **CMC Materials**

2:50 p.m. **Announcements**

3:00 p.m. *Industry Standards: From Egyptian Royal Cubit to SEMI Guides for CMP Consumables*, Alex Tregub, **Intel**

3:25p.m. *Effect of Process Variables on CMP Process Temperature*, Catherine Bullock, **Axus Technology**

3:50 p.m. *A New Kinetic Removal Rate Model for Tungsten CMP*, Ara Philipossian, **Araca Inc.**

4:15 p.m. *Preventing Cross Contamination with MIID (Malema™ Interconnect Interlock Device)*, Jay Rajagopalan, **Malema Sensors**

4:40 p.m. *Effective Slurry Concentration Monitoring Using Refractive Index*, Tracy Gast, **Entegris**

5:05 p.m. *Nanoparticle Characterization Introduction: DLS, Diffraction, and NTA*, Dr. Jeff Bodycomb, **HORIBA Scientific**

All presentations will be posted on the CMPUG Proceedings webpage within 2 weeks of conference.

If you would like to sponsor this meeting or any other User Group meeting, please check out our ["NCCA VS Marketing/Sponsorship"](#) opportunities.